1. INTRODUCTION

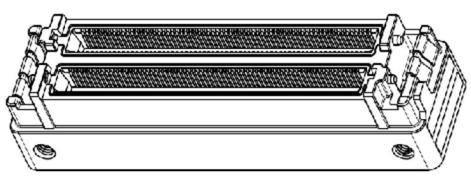
This specification covers the requirements for application of HDR and REC ASSEMBLY TC-ZIF CONNECTOR 0.8mm PITCH 260P onto printed circuit board (PC board).

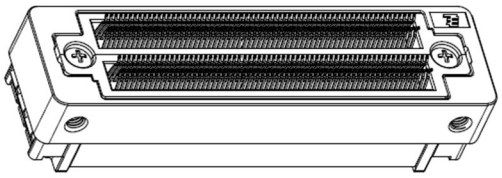
1.1. Parts number and description

Table1. Part number and description

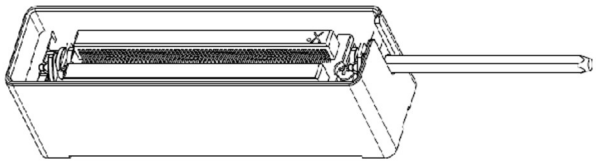
Part Number	Description
6565199-X	HDR ASSEMBLY
6565204-X	REC ASSEMBLY

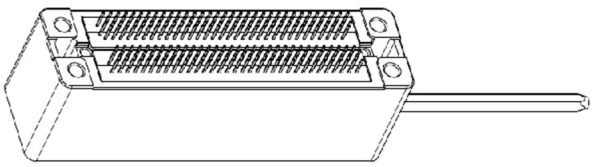
Basic terms and features of this product are provided as below.





HDR ASSEMBLY





REC ASSEMBLY

Figure .1

1.2. Prohibitions

Do not touch contacts

To prevent contact deformation, refrain to touch contacts.

3. REQUIREMENTS

3.1. Storage

A. Preferable condition

The connector should remain in the shipping containers and warehouse temperature and humidity should be controlled until ready for use to prevent deformation. The connector should be used on a first in, first out basis to avoid storage contamination that could adversely affect performance.

B. Chemical exposure

Prolonged exposure to ultraviolet light may deteriorate the chemical composition used in the connector material. Do not store connector near any chemical listed below as they may cause stress corrosion cracking in the connector.

Alkalies Ammonia Citrates Phosphates Citrates Sulfur Compounds
Amines Carbonates Nitrites Sulfur Nitrites Tartrates

3.2. HDR PC board

A. Material

The PC board material shall be glass epoxy (FR-4).

B. Thickness

The PC board thickness shall be from 1.6mm to 2.0mm.

C. Pads

The PC board circuit pads must be solder able in accordance with test specification EIA-364-52A.

D. Layouts

The circuit pads on the PC board must be precisely located to ensure proper placement and optimum performance of the connector. The PC board layout must be designed using the recommended dimensions provided in Figure 2.

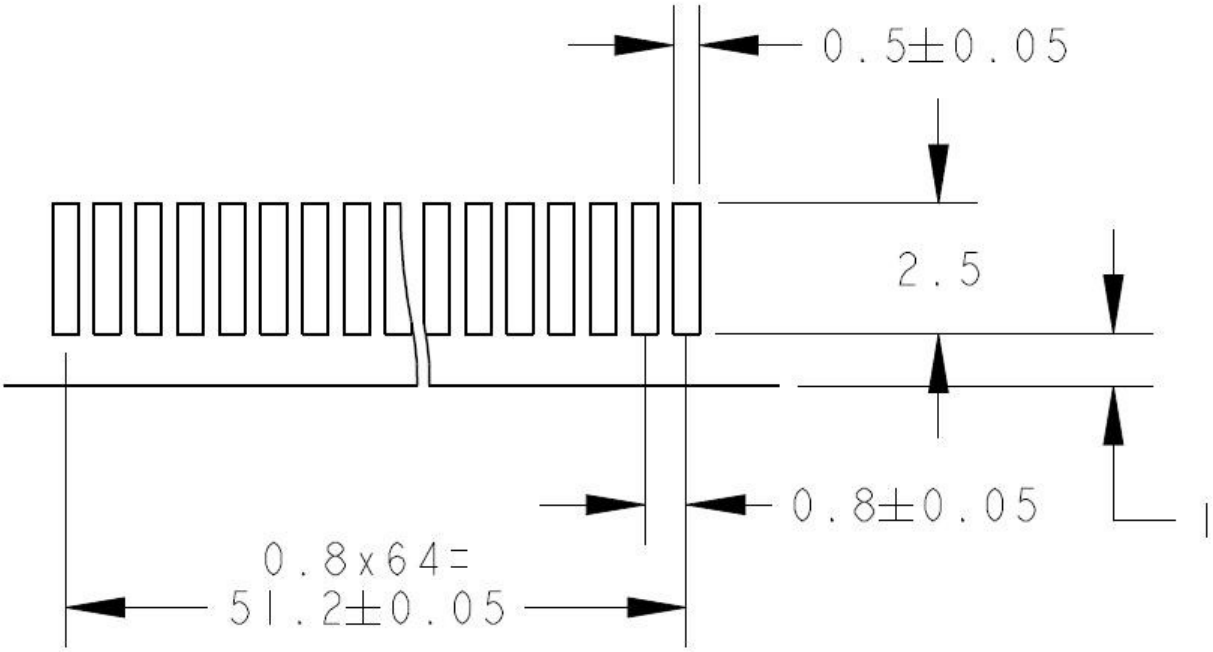


Figure .2 Reference layout (For details, please see customer drawing)

3.3. REC PC board

A. Material

The PC board material shall be glass epoxy (FR-4).

B. Pads

The PC board circuit pads must be solder able in accordance with test specification EIA-364-52A.

C. Layouts

The circuit pads on the PC board must be precisely located to ensure proper placement and optimum performance of the connector. The PC board layout must be designed using the recommended dimensions provided in Figure 3.

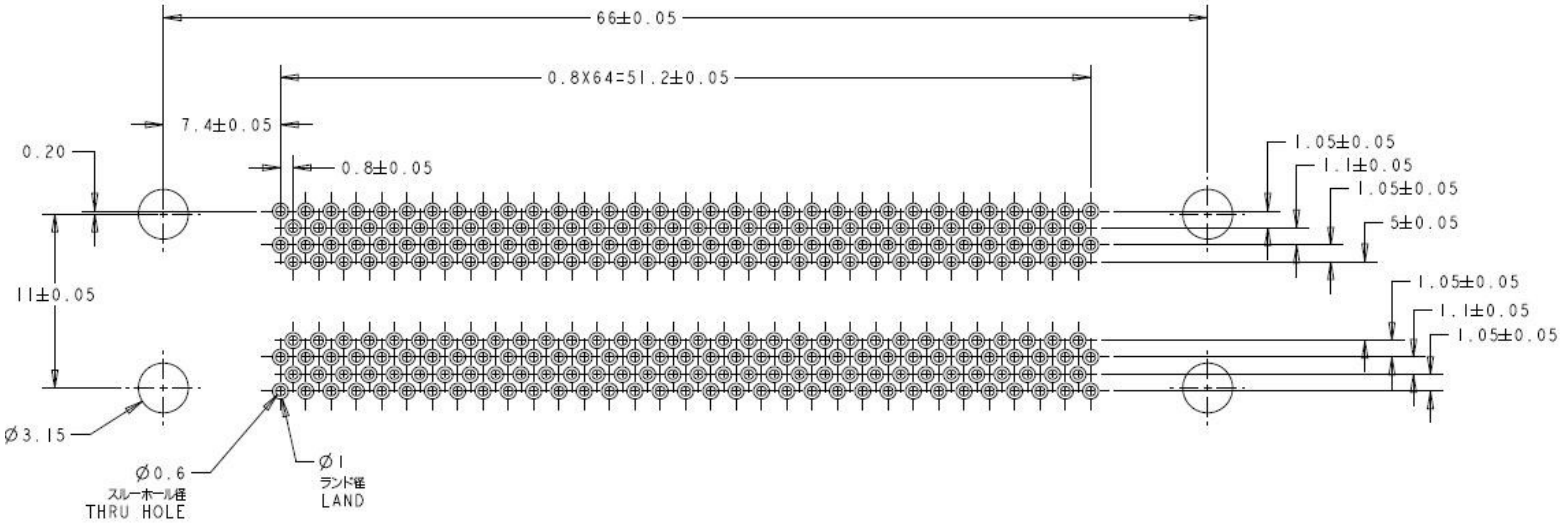
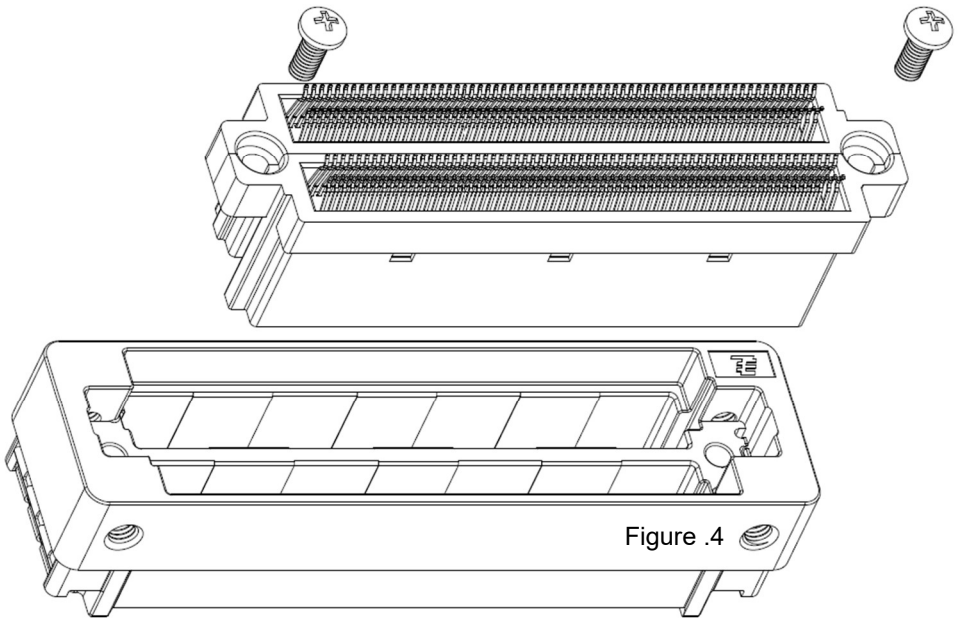


Figure .3 Reference layout (For details, please see customer drawing)

3.4. HDR Soldering

A. Preparation

Before the soldering, The HDR ASSEMBLY must be taken apart



M2.5 Screw
(Part Number: 1279657-X)

Contact
(Part Number: 2201393-X)

Base housing
(Part Number: 1871157-X)

Figure .4

Figure .4

Insert the PC board into contact

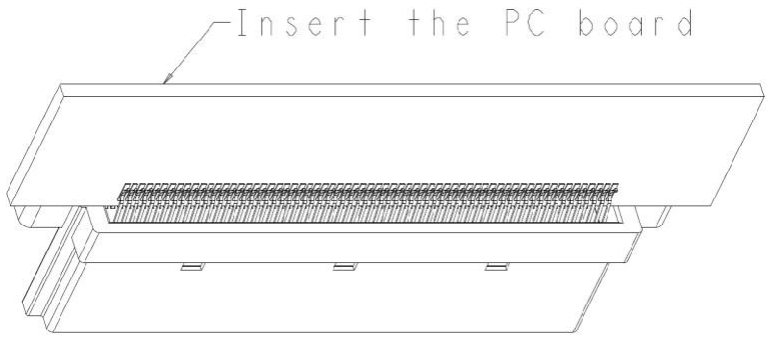


Figure .5

B. Soldering

Table2. HDR connector

Soldering process	Temperature	Time (At max temperature)	Remarks
Manual	360±10℃ (The head of top iron)	3～4 Seconds	
Reflow	260±5℃ (Peak)	10 Seconds MAX	Lead free solder

The connector assembly should be soldered to the pc board as shown in Figure.6

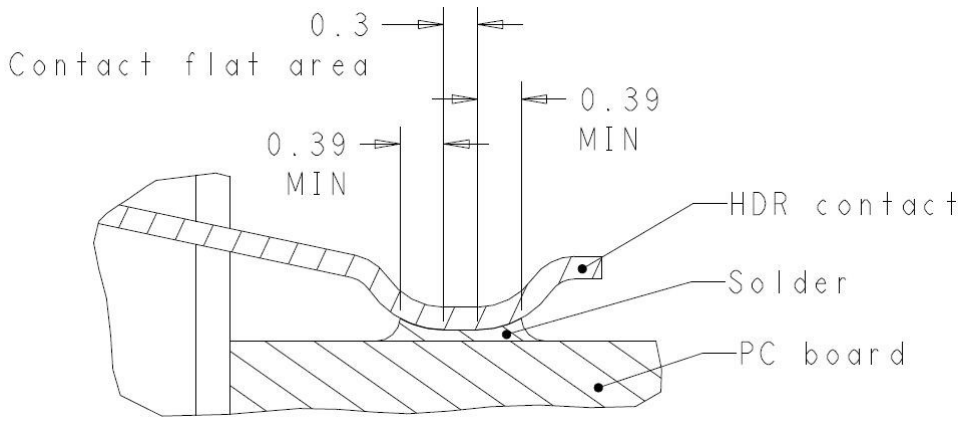


Figure .6

C. After soldering

After soldering, the HDR ASSEMBLY must be assembled.

M2.5 tightening torque: 0.36±0.036N.m

3.5. REC Soldering

A. Preparation

Before the soldering, pleases confirm the REC ASSEMBLY is in the release position.

Attempting to soldering the PC board when the actuator is not fully released will cause permanent damage to REC ASSEMBLY.

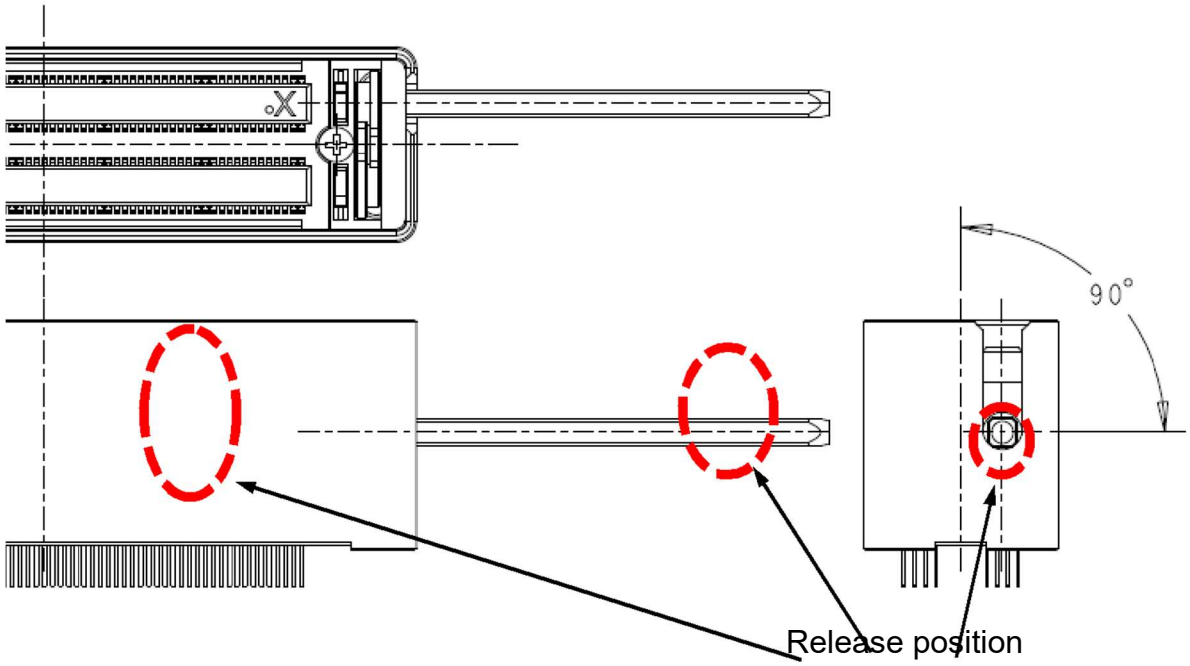


Figure .7

Before soldering, the REC ASSEMBLY must be screwed by M3 screw.

M3 tightening torque: 0.63±0.063N.m

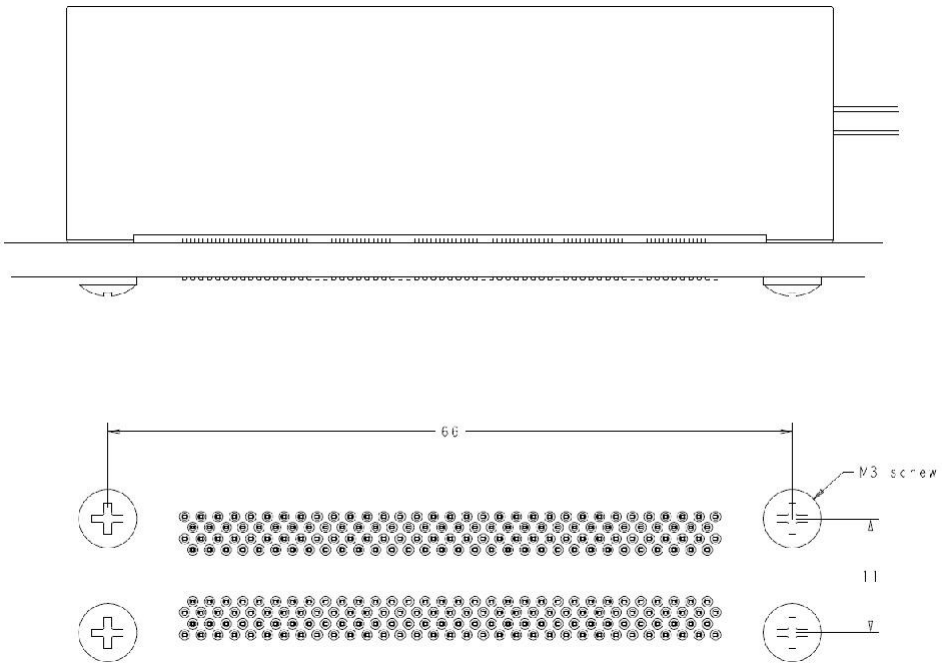


Figure .8

B. Soldering

Table2. REC connector

Soldering process	Temperature	Time (At max temperature)	Remarks
Manual	360±10℃ (The head of top iron)	3～4 Seconds	
DIP	260±5℃	10 Seconds MAX	
Reflow	N/A		

3.6. Repair or rework

The TC-ZIF Connector is not repairable.

Do not re-use the TC-ZIF connector after removing it from the PC Board.